Title (en)

PROCESSES OF FINISHING SLITS OF SURFACE LAYER OF AIRPLANE RUNWAY

Title (de)

VERFAHREN ZUM VERFÜLLEN VON FUGEN DER OBERFLÄCHENSCHICHT VON LANDEBAHNEN

Title (fr)

PROCEDES POUR RETOUCHER LES FENTES DE LA COUCHE SUPERFICIELLE D'UNE PISTE D'AVIATION

Publication

EP 1337711 A4 20050413 (EN)

Application

EP 00980259 A 20001114

Priority

US 0030137 W 20001114

Abstract (en)

[origin: WO0240806A2] A process is designed to finish all slits of the surface layer of an airplane runway. The process involves a first step in which a slit is heated such that the surface of the slit is dry, and that the capillary holes of the slit are opened up. The surface of the slit is then provided with a coating of an asphalt synthetic agent. The coating is subsequently heated to cause the molecules of the asphalt synthetic agent to diffuse into the capillary holes of the slit, thereby preventing the water from finding its way into the gradation layer of the runway. In the meantime, the slit is provided with a soft interface capable of preventing the water from finding its way into the slits of the surface layer of the runway. The soft interface is securely attached to the slits regardless of the climatic changes.

[origin: WO0240806A2] A process of finishing slits in the surface layer of a runway involves a first step in which a slit (11) is heated such that the surface of the slit (11) is dry, and that the capillary holes of the slit (11) are opened up. The surface of the slit (11) is then provided with a coating (50) of an asphalt synthetic agent. The coating (50) is subsequently heated to cause the molecules of the asphalt synthetic agent to diffuse into the capillary holes of the slit (11), thereby preventing water from finding its way into the gradation layer (A) of the runway. The slit (11) is provided with a soft interface (60) capable of preventing the water from finiding its way into the slits of the surface layer of the runway. The soft interface (60) is securely attached to the slits.

IPC 1-7

E01C 11/02; E01C 11/00; E01C 11/10; E01C 23/09; E04B 1/68; E04F 15/14

IPC 8 full level

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CPC (source: EP)

E01C 11/005 (2013.01); **E01C 11/10** (2013.01); **E01C 23/0966** (2013.01); **E04B 1/68** (2013.01); **E04B 1/6801** (2013.01); **E04F 15/14** (2013.01)

Citation (search report)

- [A] US 5236276 A 19930817 - CHANG CHUNG-HSIUNG [TW], et al
- [A] US 4324504 A 19820413 - COTTINGHAM RICHARD L, et al
- See references of WO 0240806A2

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Designated contracting state (EPC)

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